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Kind regards,

Team Nexperia
1. Product profile

1.1 General description

Ultra low capacitance unidirectional ElectroStatic Discharge (ESD) protection diodes in small Surface-Mounted Device (SMD) plastic packages designed to protect one signal line from the damage caused by ESD and other transients.

Table 1. Product overview

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Package configuration</th>
</tr>
</thead>
<tbody>
<tr>
<td>NXP</td>
<td>JEITA</td>
<td></td>
</tr>
<tr>
<td>PESD5V0U1UA</td>
<td>SOD323</td>
<td>SC-76</td>
</tr>
<tr>
<td>PESD5V0U1UB</td>
<td>SOD523</td>
<td>SC-79</td>
</tr>
<tr>
<td>PESD5V0U1UL</td>
<td>SOD882</td>
<td>-</td>
</tr>
</tbody>
</table>

1.2 Features

- Unidirectional ESD protection of one line
- Ultra low diode capacitance: $C_d = 2 \text{ pF}$
- Very low leakage current: $I_{RM} = 1 \text{ nA}$
- ESD protection up to 9 kV
- IEC 61000-4-2; level 4 (ESD)
- AEC-Q101 qualified

1.3 Applications

- USB interfaces
- 10/100/1000 Mbit/s Ethernet
- FireWire
- High-speed data lines
- Subscriber Identity Module (SIM) card protection
- Cellular handsets and accessories
- Portable electronics
- Communication systems
- Computers and peripherals
- Audio and video equipment

1.4 Quick reference data

Table 2. Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{RWM}$</td>
<td>reverse standoff voltage</td>
<td>-</td>
<td>-</td>
<td>5</td>
<td>V</td>
<td></td>
</tr>
</tbody>
</table>
2. Pinning information

Table 3. Pinning

<table>
<thead>
<tr>
<th>Pin</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>cathode</td>
<td><img src="image1" alt="Simplified outline" /></td>
<td><img src="image2" alt="Graphic symbol" /></td>
</tr>
<tr>
<td>2</td>
<td>anode</td>
<td><img src="image3" alt="Simplified outline" /></td>
<td><img src="image4" alt="Graphic symbol" /></td>
</tr>
</tbody>
</table>

PESD5V0U1UA; PESD5V0U1UB

1 cathode
2 anode

PESD5V0U1UL

1 cathode
2 anode

[1] The marking bar indicates the cathode.

3. Ordering information

Table 4. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package Name</th>
<th>Description</th>
<th>Version</th>
</tr>
</thead>
<tbody>
<tr>
<td>PESD5V0U1UA</td>
<td>SC-76</td>
<td>plastic surface-mounted package; 2 leads</td>
<td>SOD323</td>
</tr>
<tr>
<td>PESD5V0U1UB</td>
<td>SC-79</td>
<td>plastic surface-mounted package; 2 leads</td>
<td>SOD523</td>
</tr>
<tr>
<td>PESD5V0U1UL</td>
<td>-</td>
<td>leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.5 mm</td>
<td>SOD882</td>
</tr>
</tbody>
</table>

4. Marking

Table 5. Marking codes

<table>
<thead>
<tr>
<th>Type number</th>
<th>Marking code</th>
</tr>
</thead>
<tbody>
<tr>
<td>PESD5V0U1UA</td>
<td>C7</td>
</tr>
<tr>
<td>PESD5V0U1UB</td>
<td>LA</td>
</tr>
<tr>
<td>PESD5V0U1UL</td>
<td>L1</td>
</tr>
</tbody>
</table>
5. Limiting values

Table 6. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$T_j$</td>
<td>junction temperature</td>
<td></td>
<td>-</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>$T_{amb}$</td>
<td>ambient temperature</td>
<td></td>
<td>-55</td>
<td>+150</td>
<td>°C</td>
</tr>
<tr>
<td>$T_{stg}$</td>
<td>storage temperature</td>
<td></td>
<td>-65</td>
<td>+150</td>
<td>°C</td>
</tr>
</tbody>
</table>

Table 7. ESD maximum ratings
$T_{amb} = 25°C$ unless otherwise specified.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{ESD}$</td>
<td>electrostatic discharge voltage</td>
<td>IEC 61000-4-2 (contact discharge)</td>
<td>[1]</td>
<td>9</td>
<td>kV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>MIL-STD-883 (human body model)</td>
<td>-</td>
<td>10</td>
<td>kV</td>
</tr>
</tbody>
</table>


Table 8. ESD standards compliance

<table>
<thead>
<tr>
<th>Standard</th>
<th>Conditions</th>
</tr>
</thead>
<tbody>
<tr>
<td>IEC 61000-4-2; level 4 (ESD)</td>
<td>&gt; 8 kV (contact)</td>
</tr>
<tr>
<td>MIL-STD-883; class 3 (human body model)</td>
<td>&gt; 4 kV</td>
</tr>
</tbody>
</table>

Fig 1. ESD pulse waveform according to IEC 61000-4-2
6. Characteristics

Table 9. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{RWM}$</td>
<td>reverse standoff voltage</td>
<td>$V_{RWM} = 5 , V$</td>
<td>-</td>
<td>-</td>
<td>5</td>
<td>V</td>
</tr>
<tr>
<td>$I_{RM}$</td>
<td>reverse leakage current</td>
<td></td>
<td>-</td>
<td>1</td>
<td>100</td>
<td>nA</td>
</tr>
<tr>
<td>$V_{BR}$</td>
<td>breakdown voltage</td>
<td>$I_{R} = 5 , mA$</td>
<td>5.8</td>
<td>6.8</td>
<td>8.8</td>
<td>V</td>
</tr>
<tr>
<td>$C_d$</td>
<td>diode capacitance</td>
<td>$f = 1 , MHz$</td>
<td>-</td>
<td>2</td>
<td>2.6</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 0 , V$</td>
<td>-</td>
<td>1.7</td>
<td>2.3</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 5 , V$</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td>$r_{diff}$</td>
<td>differential resistance</td>
<td>$I_{R} = 1 , mA$</td>
<td>-</td>
<td>-</td>
<td>100</td>
<td>Ω</td>
</tr>
</tbody>
</table>

Fig 2. Diode capacitance as a function of reverse voltage; typical values

Fig 3. V-I characteristics for a unidirectional ESD protection diode
Fig 4. ESD clamping test setup and waveforms

IEC 61000-4-2 network
$C_Z = 150 \text{ pF}; R_Z = 330 \Omega$

unclamped +8 kV ESD pulse waveform
(IEC 61000-4-2 network)

clamped +8 kV ESD pulse waveform
(IEC 61000-4-2 network) pin 1 to 2

unclamped −8 kV ESD pulse waveform
(IEC 61000-4-2 network)

clamped −8 kV ESD pulse waveform
(IEC 61000-4-2 network) pin 1 to 2
7. Application information

The PESD5V0U1Ux series is designed for the protection of one unidirectional data or signal line from the damage caused by ESD. The devices may be used on lines where the signal polarities are either positive or negative with respect to ground.

![Application diagram](image)

**Circuit board layout and protection device placement**

Circuit board layout is critical for the suppression of ESD and Electrical Fast Transient (EFT). The following guidelines are recommended:

1. Place the device as close to the input terminal or connector as possible.
2. The path length between the device and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard **Q101 - Stress test qualification for discrete semiconductors**, and is suitable for use in automotive applications.
9. Package outline

Fig 6. Package outline
PESD5V0U1UA (SOD323/SC-76)

Fig 7. Package outline
PESD5V0U1UB (SOD523/SC-79)

Fig 8. Package outline
PESD5V0U1UL (SOD882)

10. Packing information

Table 10. Packing methods
The indicated -xxx are the last three digits of the 12NC ordering code.[1]

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Description</th>
<th>Packing quantity</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td>3000</td>
</tr>
<tr>
<td>PESD5V0U1UA</td>
<td>SOD323</td>
<td>4 mm pitch, 8 mm tape and reel</td>
<td>-115</td>
</tr>
<tr>
<td>PESD5V0U1UB</td>
<td>SOD523</td>
<td>2 mm pitch, 8 mm tape and reel</td>
<td>-</td>
</tr>
<tr>
<td></td>
<td></td>
<td>4 mm pitch, 8 mm tape and reel</td>
<td>-115</td>
</tr>
<tr>
<td>PESD5V0U1UL</td>
<td>SOD882</td>
<td>2 mm pitch, 8 mm tape and reel</td>
<td>-</td>
</tr>
</tbody>
</table>

[1] For further information and the availability of packing methods, see Section 14.
11. Soldering

Fig 9. Reflow soldering footprint PESD5V0U1UA (SOD323/SC-76)

Fig 10. Wave soldering footprint PESD5V0U1UA (SOD323/SC-76)
Refow soldering is the only recommended soldering method.

Fig 11. Reflow soldering footprint PESD5V0U1UB (SOD523/SC-79)

Fig 12. Reflow soldering footprint PESD5V0U1UL (SOD882)
12. Revision history

<table>
<thead>
<tr>
<th>Document ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
</tr>
</thead>
<tbody>
<tr>
<td>PESD5V0U1UA_UB_UL_1</td>
<td>20081030</td>
<td>Product data sheet</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>
13. Legal information

13.1 Data sheet status

<table>
<thead>
<tr>
<th>Document status</th>
<th>Product status</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>Objective [short] data sheet</td>
<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
</tr>
<tr>
<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
</tr>
<tr>
<td>Product [short] data sheet</td>
<td>Production</td>
<td>This document contains the product specification.</td>
</tr>
</tbody>
</table>

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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14. Contact information

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For sales office addresses, please send an email to: salesaddresses@nxp.com
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